

ABSTRACT

A probe card is provided in which the reliability in connection between probes 5c of a membrane and pads 23a of a wafer IC 23 has been enhanced. The base portion 12c of a mount 12 is fitted in a through-opening 4a of a printed circuit board 4. A loaded stem 8 is supported in generally the center of the mount for vertically upward and downward movement. A compression coil spring 7 is mounted around the outer periphery of the stem to apply a biasing force to the stem to urge the stem downwardly. A stiffener block 31 including a recess 31c engaged with a spherical abutment portion 8a at the lower end portion of the stem is retained by a retainer member 33 such that the stiffener block extends downwardly from the bottom surface of the printed circuit board and is movable a certain amount upwardly and horizontally against the biasing force of the coil spring. A membrane 5 formed of a flexible insulating thin film and having a plurality of probes 5c on a central area of the bottom surface thereof is attached to the bottom surface of the printed circuit board. The upper surface of the portion of the membrane including the central area is adhesively bonded to the bottom surface of the stiffener block via a resilient sheet 44.